DLAP-212 Series

Ultra-Compact Fanless Edge AI Platform with NVIDIA® Jetson Orin™ NX/Nano

Features

- Embedded with NVIDIA® Jetson Orin NX/Nano™ module, delivering up to 157 TOPS
- Supports NVIDIA Super Mode, enabling up to 1.7× AI performance, up to 1.5× memory bandwidth, and up to 2× generative AI workload acceleration
- Wide-range 12V to 24V DC input with ignition power control for in-vehicle and industrial use
- Compact, fanless design optimized for edge AI deployments in smart city, retail, and manufacturing environments
- Built-in Out-of-Band (OOB) module for remote device control

Preliminary

Ordering Information

PN	Model Name	NVIDIA Module	NVIDIA Module Memory	NVMe	DIDO/MIPI
93-45109-200E	DLAP-212 NanoS 8GB	Orin Nano	8 GB	128 GB	Y
93-45109-300E	DLAP-212 NXS 16GB	Orin NX	16 GB	128 GB	Y
93-45109-400E	DLAP-212 NXS 8GB	Orin NX	8 GB	128 GB	Y
93-45109-500E	DLAP-212 Nano 8GB	Orin Nano	8 GB	128 GB	N
93-45109-600E	DLAP-212 NX 16GB	Orin NX	16 GB	128 GB	N
93-45109-700E	DLAP-212 NX 8GB	Orin NX	8 GB	128 GB	N

Product Illustration

Specifications

Model	Orin NX 16GB	Orin NX 8G	Orin Nano 8G
AI Performance	up to 157 TOPS	up to 117 TOPS	up to 67 TOPS
System			
GPU	1024-core NVIDIA Ampere GPU with 32 Tensor Cores		
CPU	8-core Arm® Cortex®-A78AE v8.2 64-bit CPU 2MB L2 + 4MB L3	6-core Arm® Cortex®-A78AE v8.2 64-bit CPU 1.5MB L2 + 4MB L3	6-core Arm® Cortex®-A78AE v8.2 64-bit CPU 1.5MB L2 + 4MB L3
RAM	16GB	8GB	8GB
Storage	NVMe 128GB		
OS	Linux® Ubuntu		
Front I/O Interfaces			
Button	1x power		
HDMI	1x lockable		
USB	4x USB 3.2 Gen 2 Type-A		
Ethernet	2x 10/100/1000Mbps Ethernet		
DIN/DOUT	4 DI/4DO (with isolation option)		
Camera Interface	Up to 4x 2-lane MIPI CSI-2 camera interfaces (optional)		
Back I/O Interfaces			
Button	1 x reset		
USB	1x USB Type C for OTG		
Switch	1 x recovery		
COM	1x 232/422/485 on main board without isolation		
CAN Bus	1x CANbus port without isolation		
FAN	1 (Option)		
Extension Slots			
Mini PCIe	1x PCIe mini card slot (Wi-Fi/BT PCIE/USB3.0 co-layout)		
M.2	M.2 M key (2280) for OS M.2 M key (2242) for Data Storage		
Out-Of-Band (OOB)	Support Ethernet and Wi-Fi, monitoring and managing at remote locations (thermal sensor, remote power on/off, restart, monitor debug port detection device status.)		
Power Requirements			
DC Input	12-24V		
AC Input	84W, 24V, 120 up to 180W power adapter, OP Temp Max: 40°C		
Mechanical			
Dimensions (W x D x H)	148mm x 107mm x 60.2mm		
Weight	1.15 kg		
Mounting	VESA		
SMA Antenna Connector	4		
Environmental			
Operating Temperature	-20°C to 50°C with 0.6m/s airflow, at 25W (without Wi-Fi module) -20°C to 40°C with 0.6m/s airflow, at MAXN W (without Wi-Fi module)	-20°C to 60°C with 0.6m/s airflow, at 10W (without Wi-Fi module) -20°C to 50°C with 0.6m/s airflow, at 20W (without Wi-Fi module)	-20°C to 70°C with 0.6m/s airflow, at 7W (without Wi-Fi module) -20°C to 60°C with 0.6m/s airflow, at 15W (without Wi-Fi module)
Operating Humidity	~95% @40°C (non-condensing, optional with fanless solution) without adapter		
Storage Temperature	-20°C to 85°C		
Vibration	Operating 1Grms, 5-500Hz		
Shock	Operating 20G, half sine 11ms duration		
ESD	Contact ± 4kV, Air ± 8kV		
Regularity	CE & FCC class B, (EN61000-6-4/-6-2), CE-LVD & UL by CB, FCCID		
F/W Support			
WDT	WDT supported		